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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	LINbus
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	https://www.e-fl.com/product-detail/nxp-semiconductors/mc908ql4mdt

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Chapter 1

General Description

1.1 Introduction

The MC68HC908QL4 is a member of the low-cost, high-performance M68HC08 family of 8-bit microcontroller units (MCUs). All MCUs in the family use the enhanced M68HC08 central processor unit (CPU08) and are available with a variety of modules, memory sizes and types, and package types.

1.2 Features

Features include:

- High-performance M68HC08 CPU core
- Fully upward-compatible object code with M68HC05 Family
- 5-V and 3.3-V operating voltages (V_{DD})
- 8-MHz internal bus operation at 5 V, 4-MHz at 3.3 V
- Software configurable input clock from either internal or external source
- Trimmable internal oscillator
 - Selectable 1 MHz, 2 MHz, or 3.2MHz or 6.4 MHz internal bus operation
 - 8-bit trim capability
 - Trimmable to approximately 0.4%⁽¹⁾
 - $\pm 25\%$ untrimmed
- Software selectable crystal oscillator range, 32–100 kHz, 1–8 MHz, and 8–32 MHz
- Auto wakeup from STOP capability using dedicated internal 32-kHz RC or bus clock source
- On-chip in-application programmable FLASH memory
 - Internal program/erase voltage generation
 - Monitor ROM containing user callable program/erase routines
 - FLASH security⁽²⁾
- On-chip random-access memory (RAM)

1. See [17.11 Oscillator Characteristics](#) for internal oscillator specifications

2. No security feature is absolutely secure. However, Freescale's strategy is to make reading or copying the FLASH difficult for unauthorized users.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$004A	SLIC Data Register 6 (SLCD6) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$004B	SLIC Data Register 5 (SLCD5) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$004C	SLIC Data Register 4 (SLCD4) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$004D	SLIC Data Register 3 (SLCD3) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$004E	SLIC Data Register 2 (SLCD2) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$004F	SLIC Data Register 1 (SLCD1) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$0050	SLIC Data Register 0 (SLCD0) See page 149.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	0	0	0	0	0	0	0	0
\$0051 ↓ \$005F	Reserved									
\$FE00	Break Status Register (BSR) See page 191.	Read:	R	R	R	R	R	R	SBSW	R
		Write:							See note 1	
		Reset:							0	
			1. Writing a 0 clears SBSW.							
\$FE01	SIM Reset Status Register (SRSR) See page 131.	Read:	POR	PIN	COP	ILOP	ILAD	MODRST	LVI	0
		Write:								
		POR:	1	0	0	0	0	0	0	0
\$FE02	Break Auxiliary Register (BRKAR) See page 191.	Read:	0	0	0	0	0	0	0	BDCOP
		Write:								
		Reset:	0	0	0	0	0	0	0	0
			= Unimplemented			R	= Reserved		U = Unaffected	

Figure 2-2. Control, Status, and Data Registers (Sheet 5 of 7)

2.6.3 FLASH Mass Erase Operation

Use the following procedure to erase the entire FLASH memory to read as a 1:

1. Set both the ERASE bit and the MASS bit in the FLASH control register.
2. Read the FLASH block protect register.
3. Write any data to any FLASH address⁽¹⁾ within the FLASH memory address range.
4. Wait for a time, t_{NVS} .
5. Set the HVEN bit.
6. Wait for a time, t_{MErase} .
7. Clear the ERASE and MASS bits.

NOTE

Mass erase is disabled whenever any block is protected (FLBPR does not equal \$FF).

8. Wait for a time, t_{NVHL} .
9. Clear the HVEN bit.
10. After time, t_{RCV} , the memory can be accessed in read mode again.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order as shown, other unrelated operations may occur between the steps.

CAUTION

A mass erase will erase the internal oscillator trim value at \$FFC0.

1. When in monitor mode, with security sequence failed (see [16.3.2 Security](#)), write to the FLASH block protect register instead of any FLASH address.

2.6.4 FLASH Program Operation

Programming of the FLASH memory is done on a row basis. A row consists of 32 consecutive bytes starting from addresses \$XX00, \$XX20, \$XX40, \$XX60, \$XX80, \$XXA0, \$XXC0, or \$XXE0. Use the following step-by-step procedure to program a row of FLASH memory

Figure 2-4 shows a flowchart of the programming algorithm.

NOTE

Do not program any byte in the FLASH more than once after a successful erase operation. Reprogramming bits to a byte which is already programmed is not allowed without first erasing the page in which the byte resides or mass erasing the entire FLASH memory. Programming without first erasing may disturb data stored in the FLASH.

1. Set the PGM bit. This configures the memory for program operation and enables the latching of address and data for programming.
2. Read the FLASH block protect register.
3. Write any data to any FLASH location within the address range desired.
4. Wait for a time, t_{NVS} .
5. Set the HVEN bit.
6. Wait for a time, t_{PGS} .
7. Write data to the FLASH address being programmed⁽¹⁾.
8. Wait for time, t_{PROG} .
9. Repeat step 7 and 8 until all desired bytes within the row are programmed.
10. Clear the PGM bit ⁽¹⁾.
11. Wait for time, t_{NVH} .
12. Clear the HVEN bit.
13. After time, t_{RCV} , the memory can be accessed in read mode again.

NOTE

The COP register at location \$FFFF should not be written between steps 5-12, when the HVEN bit is set. Since this register is located at a valid FLASH address, unpredictable behavior may occur if this location is written while HVEN is set.

This program sequence is repeated throughout the memory until all data is programmed.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order shown, other unrelated operations may occur between the steps. Do not exceed t_{PROG} maximum, see [17.15 Memory Characteristics](#).

1. The time between each FLASH address change, or the time between the last FLASH address programmed to clearing PGM bit, must not exceed the maximum programming time, t_{PROG} maximum.

3.3.4 Sources of Error

Several sources of error exist for ADC conversions. These are discussed in the following sections.

3.3.4.1 Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately 15 k Ω and input capacitance of approximately 10 pF, sampling to within

1/4LSB (at 10-bit resolution) can be achieved within the minimum sample window (3.5 cycles / 2 MHz maximum ADCK frequency) provided the resistance of the external analog source (R_{AS}) is kept below 10 k Ω . Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

3.3.4.2 Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance (R_{AS}) is high. If this error cannot be tolerated by the application, keep R_{AS} lower than $V_{ADVIN} / (4096 \cdot I_{Leak})$ for less than 1/4LSB leakage error (at 10-bit resolution).

3.3.4.3 Noise-Induced Errors

System noise which occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC10 accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a 0.1 μ F low-ESR capacitor from V_{REFH} to V_{REFL} (if available).
- There is a 0.1 μ F low-ESR capacitor from V_{DDA} to V_{SSA} (if available).
- If inductive isolation is used from the primary supply, an additional 1 μ F capacitor is placed from V_{DDA} to V_{SSA} (if available).
- V_{SSA} and V_{REFL} (if available) is connected to V_{SS} at a quiet point in the ground plane.
- The MCU is placed in wait mode immediately after initiating the conversion (next instruction after write to ADCSC).
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive V_{DD} noise is coupled into the ADC10. In these cases, or when the MCU cannot be placed in wait or I/O activity cannot be halted, the following recommendations may reduce the effect of noise on the accuracy:

- Place a 0.01 μ F capacitor on the selected input channel to V_{REFL} or V_{SSA} (if available). This will improve noise issues but will affect sample rate based on the external analog source resistance.
- Operate the ADC10 in stop mode by setting ACLKEN, selecting the channel in ADCSC, and executing a STOP instruction. This will reduce V_{DD} noise but will increase effective conversion time due to stop recovery.
- Average the input by converting the output many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ACLKEN=1) and averaging. Noise that is synchronous to the ADCK cannot be averaged out.

4.6.2 Keyboard Status and Control Register

The keyboard status and control register (KBSCR):

- Flags keyboard/auto wakeup interrupt requests
- Acknowledges keyboard/auto wakeup interrupt requests
- Masks keyboard/auto wakeup interrupt requests

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	KEYF	0	IMASKK	MODEK
Write:						ACKK		
Reset:	0	0	0	0	0	0	0	0


 = Unimplemented

Figure 4-3. Keyboard Status and Control Register (KBSCR)

Bits 7–4 — Not used

These read-only bits always read as 0s.

KEYF — Keyboard Flag Bit

This read-only bit is set when a keyboard interrupt is pending on port A or auto wakeup. Reset clears the KEYF bit.

- 1 = Keyboard/auto wakeup interrupt pending
- 0 = No keyboard/auto wakeup interrupt pending

ACKK — Keyboard Acknowledge Bit

Writing a 1 to this write-only bit clears the keyboard/auto wakeup interrupt request on port A and auto wakeup logic. ACKK always reads as 0. Reset clears ACKK.

IMASKK— Keyboard Interrupt Mask Bit

Writing a 1 to this read/write bit prevents the output of the keyboard interrupt mask from generating interrupt requests on port A or auto wakeup. Reset clears the IMASKK bit.

- 1 = Keyboard/auto wakeup interrupt requests masked
- 0 = Keyboard/auto wakeup interrupt requests not masked

NOTE

MODEK is not used in conjunction with the auto wakeup feature. To see a description of this bit, see [9.8.1 Keyboard Status and Control Register \(KBSCR\)](#).

4.6.3 Keyboard Interrupt Enable Register

The keyboard interrupt enable register (KBIER) enables or disables the auto wakeup to operate as a keyboard/auto wakeup interrupt input.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	AWUIE	KBIE5	KBIE4	KBIE3	KBIE2	KBIE1	KBIE0
Write:								
Reset:	0	0	0	0	0	0	0	0

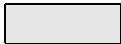
 = Unimplemented

Figure 4-4. Keyboard Interrupt Enable Register (KBIER)

AWUIE — Auto Wakeup Interrupt Enable Bit

This read/write bit enables the auto wakeup interrupt input to latch interrupt requests. Reset clears AWUIE.

1 = Auto wakeup enabled as interrupt input

0 = Auto wakeup not enabled as interrupt input

NOTE

KBIE5–KBIE0 bits are not used in conjunction with the auto wakeup feature. To see a description of these bits, see [9.8.2 Keyboard Interrupt Enable Register \(KBIER\)](#).

4.6.4 Configuration Register 2

The configuration register 2 (CONFIG2), is used to allow the bus clock source to run in STOP. In this case, the clock, BUSCLKX2 will be used to drive the AWU request generator.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IRQPUD	IRQEN	R	R	R	R	OSCENINSTOP	RSTEN
Write:								
Reset:	0	0	0	0	0	0	0	0

Figure 4-5. Configuration Register 2 (CONFIG2)

OSCENINSTOP — Oscillator Enable in Stop Mode Bit

OSCENINSTOP, when set, will allow the bus clock source (BUSCLKX2) to generate clocks for the AWU in stop mode. See [11.8.1 Oscillator Status and Control Register](#) for information on enabling the external clock sources.

1 = Oscillator enabled to operate during stop mode

0 = Oscillator disabled during stop mode

NOTE

IRQPUD, IRQEN, and RSTEN bits are not used in conjunction with the auto wakeup feature. To see a description of these bits, see [Chapter 5 Configuration Register \(CONFIG\)](#).

4.6.5 Configuration Register 1

The configuration register 1 (CONFIG1), is used to select the period for the AWU. The timeout will be based on the COPRS bit along with the clock source for the AWU.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVITRIP	SSREC	STOP	COPD
Write:								
Reset: POR:	0	0	0	0	U	0	0	0
	0	0	0	0	0	0	0	0

U = Unaffected

Figure 4-6. Configuration Register 1 (CONFIG1)

Computer Operating Properly (COP)

The COP counter is a free-running 6-bit counter preceded by the 12-bit system integration module (SIM) counter. If not cleared by software, the COP counter overflows and generates an asynchronous reset after 262,128 or 8176 BUSCLKX4 cycles; depending on the state of the COP rate select bit, COPRS, in configuration register 1. With a 262,128 BUSCLKX4 cycle overflow option, the internal 12.8-MHz oscillator gives a COP timeout period of 20.48 ms. Writing any value to location \$FFFF before an overflow occurs prevents a COP reset by clearing the COP counter and stages 12–5 of the SIM counter.

NOTE

Service the COP immediately after reset and before entering or after exiting stop mode to guarantee the maximum time before the first COP counter overflow.

A COP reset pulls the $\overline{\text{RST}}$ pin low (if the RSTEN bit is set in the CONFIG1 register) for $32 \times \text{BUSCLKX4}$ cycles and sets the COP bit in the reset status register (RSR). See [13.8.1 SIM Reset Status Register](#).

NOTE

Place COP clearing instructions in the main program and not in an interrupt subroutine. Such an interrupt subroutine could keep the COP from generating a reset even while the main program is not working properly.

6.3 I/O Signals

The following paragraphs describe the signals shown in [Figure 6-1](#).

6.3.1 BUSCLKX4

BUSCLKX4 is the oscillator output signal. BUSCLKX4 frequency is equal to the crystal frequency or the RC-oscillator frequency.

6.3.2 STOP Instruction

The STOP instruction clears the SIM counter.

6.3.3 COPCTL Write

Writing any value to the COP control register (COPCTL) (see [Figure 6-2](#)) clears the COP counter and clears stages 12–5 of the SIM counter. Reading the COP control register returns the low byte of the reset vector.

6.3.4 Power-On Reset

The power-on reset (POR) circuit in the SIM clears the SIM counter $4096 \times \text{BUSCLKX4}$ cycles after power up.

6.3.5 Internal Reset

An internal reset clears the SIM counter and the COP counter.

6.3.6 COPD (COP Disable)

The COPD signal reflects the state of the COP disable bit (COPD) in the configuration register (CONFIG). See [Chapter 5 Configuration Register \(CONFIG\)](#).

7.3.5 Condition Code Register

The 8-bit condition code register contains the interrupt mask and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code register.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	V	1	1	H	I	N	Z	C
Write:								
Reset:	X	1	1	X	1	X	X	X

X = Indeterminate

Figure 7-6. Condition Code Register (CCR)

V — Overflow Flag

The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag.

- 1 = Overflow
- 0 = No overflow

H — Half-Carry Flag

The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C flags to determine the appropriate correction factor.

- 1 = Carry between bits 3 and 4
- 0 = No carry between bits 3 and 4

I — Interrupt Mask

When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the interrupt vector is fetched.

- 1 = Interrupts disabled
- 0 = Interrupts enabled

NOTE

To maintain M6805 Family compatibility, the upper byte of the index register (H) is not stacked automatically. If the interrupt service routine modifies H, then the user must stack and unstack H using the PSHH and PULH instructions.

After the I bit is cleared, the highest-priority interrupt request is serviced first.

A return-from-interrupt (RTI) instruction pulls the CPU registers from the stack and restores the interrupt mask from the stack. After any reset, the interrupt mask is set and can be cleared only by the clear interrupt mask software instruction (CLI).

N — Negative Flag

The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result.

- 1 = Negative result
- 0 = Non-negative result

Table 7-1. Instruction Set Summary (Sheet 5 of 6)

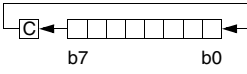
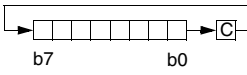
Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z				
PULA	Pull A from Stack	$SP \leftarrow (SP + 1); \text{Pull (A)}$	–	–	–	–	–	INH	86		2
PULH	Pull H from Stack	$SP \leftarrow (SP + 1); \text{Pull (H)}$	–	–	–	–	–	INH	8A		2
PULX	Pull X from Stack	$SP \leftarrow (SP + 1); \text{Pull (X)}$	–	–	–	–	–	INH	88		2
ROL <i>opr</i> ROLA ROLX ROL <i>opr</i> ,X ROL ,X ROL <i>opr</i> ,SP	Rotate Left through Carry		↑	–	–	–	↑	DIR INH INH IX1 IX SP1	39 49 59 69 79 9E69	dd ff ff	4 1 1 4 3 5
ROR <i>opr</i> RORA RORX ROR <i>opr</i> ,X ROR ,X ROR <i>opr</i> ,SP	Rotate Right through Carry		↑	–	–	–	↑	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	4 1 1 4 3 5
RSP	Reset Stack Pointer	$SP \leftarrow \$FF$	–	–	–	–	–	INH	9C		1
RTI	Return from Interrupt	$SP \leftarrow (SP + 1); \text{Pull (CCR)}$ $SP \leftarrow (SP + 1); \text{Pull (A)}$ $SP \leftarrow (SP + 1); \text{Pull (X)}$ $SP \leftarrow (SP + 1); \text{Pull (PCH)}$ $SP \leftarrow (SP + 1); \text{Pull (PCL)}$	↑	↑	↑	↑	↑	INH	80		7
RTS	Return from Subroutine	$SP \leftarrow SP + 1; \text{Pull (PCH)}$ $SP \leftarrow SP + 1; \text{Pull (PCL)}$	–	–	–	–	–	INH	81		4
SBC # <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> ,X SBC <i>opr</i> ,X SBC ,X SBC <i>opr</i> ,SP SBC <i>opr</i> ,SP	Subtract with Carry	$A \leftarrow (A) - (M) - (C)$	↑	–	–	–	↑	IMM DIR EXT IX2 IX1 IX SP1 SP2	A2 B2 C2 D2 E2 F2 9EE2 9ED2	ii dd hh ll ee ff ff ff ff ff ee ff	2 3 4 4 3 2 4 5
SEC	Set Carry Bit	$C \leftarrow 1$	–	–	–	–	1	INH	99		1
SEI	Set Interrupt Mask	$I \leftarrow 1$	–	–	1	–	–	INH	9B		2
STA <i>opr</i> STA <i>opr</i> STA <i>opr</i> ,X STA <i>opr</i> ,X STA ,X STA <i>opr</i> ,SP STA <i>opr</i> ,SP	Store A in M	$M \leftarrow (A)$	0	–	–	–	↑	DIR EXT IX2 IX1 IX SP1 SP2	B7 C7 D7 E7 F7 9EE7 9ED7	dd hh ll ee ff ff ff ff ff ee ff	3 4 4 3 2 4 5
STHX <i>opr</i>	Store H:X in M	$(M:M + 1) \leftarrow (H:X)$	0	–	–	–	↑	DIR	35	dd	4
STOP	Enable Interrupts, Stop Processing, Refer to MCU Documentation	$I \leftarrow 0$; Stop Processing	–	–	0	–	–	INH	8E		1
STX <i>opr</i> STX <i>opr</i> STX <i>opr</i> ,X STX <i>opr</i> ,X STX ,X STX <i>opr</i> ,SP STX <i>opr</i> ,SP	Store X in M	$M \leftarrow (X)$	0	–	–	–	↑	DIR EXT IX2 IX1 IX SP1 SP2	BF CF DF EF FF 9EEF 9EDF	dd hh ll ee ff ff ff ff ff ee ff	3 4 4 3 2 4 5
SUB # <i>opr</i> SUB <i>opr</i> SUB <i>opr</i> SUB <i>opr</i> ,X SUB <i>opr</i> ,X SUB ,X SUB <i>opr</i> ,SP SUB <i>opr</i> ,SP	Subtract	$A \leftarrow (A) - (M)$	↑	–	–	–	↑	IMM DIR EXT IX2 IX1 IX SP1 SP2	A0 B0 C0 D0 E0 F0 9EE0 9ED0	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5

Table 7-2. Opcode Map

	Bit Manipulation		Branch	Read-Modify-Write						Control		Register/Memory							
	DIR	DIR	REL	DIR	INH	INH	IX1	SP1	IX	INH	INH	IMM	DIR	EXT	IX2	SP2	IX1	SP1	IX
MSB LSB	0	1	2	3	4	5	6	9E6	7	8	9	A	B	C	D	9ED	E	9EE	F
0	BRSET0 3 DIR	BSET0 2 DIR	BRA 2 REL	NEG 2 DIR	NEGA 1 INH	NEGX 1 INH	NEG 2 IX1	NEG 3 SP1	NEG 1 IX	RTI 1 INH	BGE 2 REL	SUB 2 IMM	SUB 2 DIR	SUB 3 EXT	SUB 3 IX2	SUB 4 SP2	SUB 2 IX1	SUB 3 SP1	SUB 1 IX
1	BRCLR0 3 DIR	BCLR0 2 DIR	BRN 2 REL	CBEQ 3 DIR	CBEQA 3 IMM	CBEQX 3 IMM	CBEQ 3 IX1+	CBEQ 4 SP1	CBEQ 2 IX+	RTS 1 INH	BLT 2 REL	CMP 2 IMM	CMP 2 DIR	CMP 3 EXT	CMP 3 IX2	CMP 4 SP2	CMP 2 IX1	CMP 3 SP1	CMP 1 IX
2	BRSET1 3 DIR	BSET1 2 DIR	BHI 2 REL		MUL 1 INH	DIV 1 INH	NSA 1 INH		DAA 1 INH		BGT 2 REL	SBC 2 IMM	SBC 2 DIR	SBC 3 EXT	SBC 3 IX2	SBC 4 SP2	SBC 2 IX1	SBC 3 SP1	SBC 1 IX
3	BRCLR1 3 DIR	BCLR1 2 DIR	BLS 2 REL	COM 2 DIR	COMA 1 INH	COMX 1 INH	COM 2 IX1	COM 3 SP1	COM 1 IX	SWI 1 INH	BLE 2 REL	CPX 2 IMM	CPX 2 DIR	CPX 3 EXT	CPX 3 IX2	CPX 4 SP2	CPX 2 IX1	CPX 3 SP1	CPX 1 IX
4	BRSET2 3 DIR	BSET2 2 DIR	BCC 2 REL	LSR 2 DIR	LSRA 1 INH	LSRX 1 INH	LSR 2 IX1	LSR 3 SP1	LSR 1 IX	TAP 1 INH	TXS 1 INH	AND 2 IMM	AND 2 DIR	AND 3 EXT	AND 3 IX2	AND 4 SP2	AND 2 IX1	AND 3 SP1	AND 1 IX
5	BRCLR2 3 DIR	BCLR2 2 DIR	BCS 2 REL	STHX 2 DIR	LDHX 3 IMM	LDHX 2 DIR	CPHX 3 IMM		CPHX 2 DIR	TPA 1 INH	TSX 1 INH	BIT 2 IMM	BIT 2 DIR	BIT 3 EXT	BIT 3 IX2	BIT 4 SP2	BIT 2 IX1	BIT 3 SP1	BIT 1 IX
6	BRSET3 3 DIR	BSET3 2 DIR	BNE 2 REL	ROR 2 DIR	RORA 1 INH	RORX 1 INH	ROR 2 IX1	ROR 3 SP1	ROR 1 IX	PULA 1 INH		LDA 2 IMM	LDA 2 DIR	LDA 3 EXT	LDA 3 IX2	LDA 4 SP2	LDA 2 IX1	LDA 3 SP1	LDA 1 IX
7	BRCLR3 3 DIR	BCLR3 2 DIR	BEQ 2 REL	ASR 2 DIR	ASRA 1 INH	ASRX 1 INH	ASR 2 IX1	ASR 3 SP1	ASR 1 IX	PSHA 1 INH	TAX 1 INH	AIS 2 IMM	STA 2 DIR	STA 3 EXT	STA 3 IX2	STA 4 SP2	STA 2 IX1	STA 3 SP1	STA 1 IX
8	BRSET4 3 DIR	BSET4 2 DIR	BHCC 2 REL	LSL 2 DIR	LSLA 1 INH	LSLX 1 INH	LSL 2 IX1	LSL 3 SP1	LSL 1 IX	PULX 1 INH	CLC 1 INH	EOR 2 IMM	EOR 2 DIR	EOR 3 EXT	EOR 3 IX2	EOR 4 SP2	EOR 2 IX1	EOR 3 SP1	EOR 1 IX
9	BRCLR4 3 DIR	BCLR4 2 DIR	BHCS 2 REL	ROL 2 DIR	ROLA 1 INH	ROLX 1 INH	ROL 2 IX1	ROL 3 SP1	ROL 1 IX	PSHX 1 INH	SEC 1 INH	ADC 2 IMM	ADC 2 DIR	ADC 3 EXT	ADC 3 IX2	ADC 4 SP2	ADC 2 IX1	ADC 3 SP1	ADC 1 IX
A	BRSET5 3 DIR	BSET5 2 DIR	BPL 2 REL	DEC 2 DIR	DECA 1 INH	DECX 1 INH	DEC 2 IX1	DEC 3 SP1	DEC 1 IX	PULH 1 INH	CLI 1 INH	ORA 2 IMM	ORA 2 DIR	ORA 3 EXT	ORA 3 IX2	ORA 4 SP2	ORA 2 IX1	ORA 3 SP1	ORA 1 IX
B	BRCLR5 3 DIR	BCLR5 2 DIR	BMI 2 REL	DBNZ 3 DIR	DBNZA 2 INH	DBNZX 2 INH	DBNZ 3 IX1	DBNZ 4 SP1	DBNZ 2 IX	PSHH 1 INH	SEI 1 INH	ADD 2 IMM	ADD 2 DIR	ADD 3 EXT	ADD 3 IX2	ADD 4 SP2	ADD 2 IX1	ADD 3 SP1	ADD 1 IX
C	BRSET6 3 DIR	BSET6 2 DIR	BMC 2 REL	INC 2 DIR	INCA 1 INH	INCX 1 INH	INC 2 IX1	INC 3 SP1	INC 1 IX	CLRH 1 INH	RSP 1 INH		JMP 2 DIR	JMP 3 EXT	JMP 3 IX2		JMP 2 IX1		JMP 1 IX
D	BRCLR6 3 DIR	BCLR6 2 DIR	BMS 2 REL	TST 2 DIR	TSTA 1 INH	TSTX 1 INH	TST 2 IX1	TST 3 SP1	TST 1 IX		NOP 1 INH	BSR 2 REL	JSR 2 DIR	JSR 3 EXT	JSR 3 IX2		JSR 2 IX1		JSR 1 IX
E	BRSET7 3 DIR	BSET7 2 DIR	BIL 2 REL		MOV 3 DD	MOV 2 DIX+	MOV 3 IMD		MOV 2 IX+D	STOP 1 INH	*	LDX 2 IMM	LDX 2 DIR	LDX 3 EXT	LDX 3 IX2	LDX 4 SP2	LDX 2 IX1	LDX 3 SP1	LDX 1 IX
F	BRCLR7 3 DIR	BCLR7 2 DIR	BIH 2 REL	CLR 2 DIR	CLRA 1 INH	CLRAX 1 INH	CLR 2 IX1	CLR 3 SP1	CLR 1 IX	WAIT 1 INH	TXA 1 INH	AIX 2 IMM	STX 2 DIR	STX 3 EXT	STX 3 IX2	STX 4 SP2	STX 2 IX1	STX 3 SP1	STX 1 IX

INH Inherent
IMM Immediate
DIR Direct
EXT Extended
DD Direct-Direct
IX+D Indexed-Direct

REL Relative
IX Indexed, No Offset
IX1 Indexed, 8-Bit Offset
IX2 Indexed, 16-Bit Offset
IMD Immediate-Direct
DIX+ Direct-Indexed

SP1 Stack Pointer, 8-Bit Offset
SP2 Stack Pointer, 16-Bit Offset
IX+ Indexed, No Offset with Post Increment
IX1+ Indexed, 1-Byte Offset with Post Increment

*Pre-byte for stack pointer indexed instructions

Low Byte of Opcode in Hexadecimal

MSB LSB	0	High Byte of Opcode in Hexadecimal
0	5 BRSET0 3 DIR	Cycles Opcode Mnemonic Number of Bytes / Addressing Mode

Figure 11-3 shows how BUSCLKX4 is derived from INTCLK and OSC2 can output BUSCLKX4 by setting OSC2EN.

11.3.2.1 Internal Oscillator Trimming

OSCTRIM allows a clock period adjustment of +127 and –128 steps. Increasing the OSCTRIM value increases the clock period, which decreases the clock frequency. Trimming allows the internal clock frequency to be fine tuned to the target frequency.

All devices are factory programmed with a trim value that is stored in FLASH memory at location \$FFC0. The trim value is not automatically loaded into the OSCTRIM register. User software must copy the trim value from \$FFC0 into OSCTRIM if needed. The factory trim value provides the accuracy required for communication using forced monitor mode. Some production programmers erase the factory trim value, so confirm with your programmer vendor that the trim value at \$FFC0 is preserved, or is re-trimmed. Trimming the device in the user application board will provide the most accurate trim value.

11.3.2.2 Internal to External Clock Switching

When external clock source (external OSC, RC, or XTAL) is desired, the user must perform the following steps:

1. For external crystal circuits only, configure OSCOPT[1:0] to external crystal. To help precharge an external crystal oscillator, momentarily configure OSC2 as an output and drive it high for several cycles. This can help the crystal circuit start more robustly.
2. Configure OSCOPT[1:0] and ECFS[1:0] according to [11.8.1 Oscillator Status and Control Register](#). The oscillator module control logic will then enable OSC1 as an external clock input and, if the external crystal option is selected, OSC2 will also be enabled as the clock output. If RC oscillator option is selected, enabling the OSC2 output may change the bus frequency.
3. Create a software delay to provide the stabilization time required for the selected clock source (crystal, resonator, RC). A good rule of thumb for crystal oscillators is to wait 4096 cycles of the crystal frequency; i.e., for a 4-MHz crystal, wait approximately 1 ms.
4. After the stabilization delay has elapsed, set ECGON.

After ECGON set is detected, the OSC module checks for oscillator activity by waiting two external clock rising edges. The OSC module then switches to the external clock. Logic provides a coherent transition. The OSC module first sets ECGST and then stops the internal oscillator.

11.3.2.3 External to Internal Clock Switching

After following the procedures to switch to an external clock source, it is possible to go back to the internal source. By clearing the OSCOPT[1:0] bits and clearing the ECGON bit, the external circuit will be disengaged. The bus clock will be derived from the selected internal clock source based on the ICFS[1:0] bits.

11.3.3 External Oscillator

The external oscillator option is designed for use when a clock signal is available in the application to provide a clock source to the MCU. The OSC1 pin is enabled as an input by the oscillator module. The clock signal is used directly to create BUSCLKX4 and also divided by two to create BUSCLKX2.

In this configuration, the OSC2 pin cannot output BUSCLKX4. The OSC2EN bit will be forced clear to enable alternative functions on the pin.

Input/Output Ports (PORTS)

PTAPUE[5:0] — Port A Input Pullup/Down Enable Bits

These read/write bits are software programmable to enable pullup/down devices on port A pins.

1 = Corresponding port A pin configured to have internal pullup/down if its DDRA bit is set to 0

0 = Pullup/down device is disconnected on the corresponding port A pin regardless of the state of its DDRA bit

12.3.4 Port A Summary Table

The following table summarizes the operation of the port A pins when used as a general-purpose input/output pins.

Table 12-1. Port A Pin Functions

PTAPUE Bit	DDRA Bit	PTA Bit	I/O Pin Mode	Accesses to DDRA	Accesses to PTA	
				Read/Write	Read	Write
1	0	X ⁽¹⁾	Input, V_{Pull} ⁽²⁾	DDRA5–DDRA0	Pin	PTA5–PTA0 ⁽³⁾
0	0	X	Input, Hi-Z ⁽⁴⁾	DDRA5–DDRA0	Pin	PTA5–PTA0 ⁽³⁾
X	1	X	Output	DDRA5–DDRA0	PTA5–PTA0	PTA5–PTA0 ⁽⁵⁾

1. X = don't care

2. I/O pin pulled to V_{Pull} (V_{DD} or V_{SS}) by internal pullup or pulldown.

3. Writing affects data register, but does not affect input.

4. Hi-Z = high impedance

5. Output does not apply to PTA2

12.4 Port B

Port B is an 8-bit special function port that shares its pins with the 2-channel timer interface module (TIM) (see [Chapter 15 Timer Interface Module \(TIM\)](#)), the 10-bit ADC (see [Chapter 3 Analog-to-Digital Converter \(ADC10\) Module](#)), and the slave LIN interface controller (SLIC) module (see [Chapter 14 Slave LIN Interface Controller \(SLIC\) Module](#)).

Each port B pin also has a software configurable pullup device if the corresponding port pin is configured as an input port.

12.4.1 Port B Data Register

The port B data register (PTB) contains a data latch for each of the port B pins.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	PTB7	PTB6	PTB5	PTB4	PTB3	PTB2	PTB1	PTB0
Write:								
Reset:	Unaffected by reset							

Figure 12-5. Port B Data Register (PTB)

PTB[7:0] — Port B Data Bits

These read/write bits are software programmable. Data direction of each port B pin is under the control of the corresponding bit in data direction register B. Reset has no effect on port B data.

IMSG — SLIC Ignore Message Bit

IMSG cannot be cleared by a write of 0, but is cleared automatically by the SLIC module after the next BREAK/SYNC symbol pair is validated. After it is set, IMSG will not keep data from being written to the receive data buffer, which means that the buffers cannot be assumed to contain known valid message data until the next receive buffer full interrupt. IMSG must not be used in BTM mode.

- 1 = SLIC to ignore data field of message, SLIC interrupts are suppressed until the next message header arrives
- 0 = Normal operation

SLCIE — SLIC Interrupt Enable

- 1 = SLIC interrupt sources are enabled
- 0 = SLIC interrupt sources are disabled

14.8.2 SLIC Control Register 2

SLIC control register 2 (SLCC2) contains bits used to control various features of the SLIC module.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	SLCWCM	BTM	0	SLCE
Write:								
Reset:	0	0	0	0	0	0	0	0

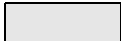
 = Unimplemented

Figure 14-5. SLIC Control Register 2 (SLCC2)

SLCWCM — SLIC Wait Clock Mode

This bit can only be written once out of reset state.

- 1 = SLIC clocks stop when the CPU is placed into wait mode
- 0 = SLIC clocks continue to run when the CPU is placed into wait mode so that the SLIC can receive messages and wakeup the CPU.

BTM — UART Byte Transfer Mode

Byte transmit mode bypasses the normal LIN message framing and checksum monitoring and allows the user to send and receive single bytes in a method similar to a half-duplex UART. When enabled, this mode reads the bit time register (SLCBT) value and assumes this is the value corresponding to the number of SLIC clock counts for one bit time to establish the desired UART bit rate. The user software must initialize this register prior to sending or receiving data, based on the input clock selection, prescaler stage choice, and desired bit rate.

BTM forces the data length in SLCDLC to one byte (DLC = 0x00) and disables the checksum circuitry so that CHKMOD has no effect. Refer to [14.9.15 Byte Transfer Mode Operation](#) for more detailed information about how to use this mode. BTM sets up the SLIC module to send and receive one byte at a time, with 8-bit data, no parity, and one stop bit (8-N-1). This is the most commonly used setup for UART communications and should work for most applications. This is fixed in the SLIC and is not configurable.

- 1 = UART byte transfer mode enabled
- 0 = UART byte transfer mode disabled

SLCE — SLIC Module Enable

- 1 = SLIC module enabled
- 0 = SLIC module disabled

14.9.7.1 LIN Message Headers

All LIN message frame headers are comprised of three components:

- The first is the SYNCHRONIZATION BREAK (SYNCH BREAK) symbol, which is a dominant (low) pulse at least 13 or more bit times long, followed by a recessive (high) synchronization delimiter of at least one bit time. In LIN 2.0, this is allowed to be 10 or more bit times in length.
- The second part is called the SYNCHRONIZATION FIELD (SYNCH FIELD) and is a single byte with value 0x55. This value was chosen as it is the only one which provides a series of five falling (recessive to dominant) transitions on the bus.
- The third section of the message frame header is the IDENTIFIER FIELD (ID). The identifier is covered more in [14.9.8 Handling Command Message Frames](#) and [14.9.9 Handling Request LIN Message Frames](#).

The SLIC automatically reads the incoming pattern of the SYNCHRONIZATION BREAK and FIELD and determines the bit rate of the LIN data frame, as well as checking for errors in form and discerning between a genuine BREAK/FIELD combination and a similar byte pattern somewhere in the data stream. After the header has been verified to be valid and has been processed, the SLIC module updates the SLIC bit time register (SLCBT) with the value obtained from the SYNCH FIELD and begins to receive the ID.

If there are errors in the SYNCH BREAK/FIELD pattern, then an interrupt is generated. If unmasked, it will trigger an MCU interrupt request and the resulting code in the SLIC state vector register (SLCSV) will be an “Inconsistent-Synch-Field-Error,” based on the LIN protocol specification.

After the ID for the message frame has been received, an interrupt is generated by the SLIC and will trigger an MCU interrupt request if unmasked. At this point, it might be possible that the ID was received with errors such as a parity error (based on the LIN specification) or a byte framing error. If the ID did not have any errors, it will be copied into the SLCD for the software to read. The SLCV will indicate the type error or that the ID was received correctly.

In a LIN system, the meaning and function of all messages, and therefore all message identifiers, is pre-defined by the system designer. This information can be collected and stored in a standardized format file, called a Configuration Language Description (CLD) file. In using the SLIC module, it is the responsibility of the user software to determine the nature of the incoming message, and therefore how to further handle that message.

The simplest case is when the SLIC receives a message which the user software determines is of no interest to the application. In other words, the slave node does not need to receive or transmit any data for this message frame. This might also apply to messages with zero data bytes (which is allowed by the LIN specification). At this point, the user can set the IMMSG control bit, and exit the interrupt service routine by clearing the SLCIF flag. Because there is no data to be sent or received, the SLIC will not generate another interrupt until the next message frame header or bus goes idle long enough to trigger a “No-Bus-Activity” error according to the LIN specification.

NOTE

IMMSG will prevent another interrupt from occurring for the current message frame; however, if data bytes are appearing on the bus they may be received and copied into the message buffer. This will delete any previous data which might have been present in the buffer, even though no interrupt is triggered to indicate the arrival of this data.

15.4 Interrupts

The following TIM sources can generate interrupt requests:

- TIM overflow flag (TOF) — The TOF bit is set when the counter reaches the modulo value programmed in the TIM counter modulo registers. The TIM overflow interrupt enable bit, TOIE, enables TIM overflow interrupt requests. TOF and TOIE are in the TSC register.
- TIM channel flags (CH1F:CH0F) — The CHxF bit is set when an input capture or output compare occurs on channel x. Channel x TIM interrupt requests are controlled by the channel x interrupt enable bit, CHxIE. Channel x TIM interrupt requests are enabled when CHxIE = 1. CHxF and CHxIE are in the TSCx register.

15.5 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

15.5.1 Wait Mode

The TIM remains active after the execution of a WAIT instruction. In wait mode the TIM registers are not accessible by the CPU. Any enabled interrupt request from the TIM can bring the MCU out of wait mode.

If TIM functions are not required during wait mode, reduce power consumption by stopping the TIM before executing the WAIT instruction.

15.5.2 Stop Mode

The TIM module is inactive after the execution of a STOP instruction. The STOP instruction does not affect register conditions. TIM operation resumes after an external interrupt. If stop mode is exited by reset, the TIM is reset.

15.6 TIM During Break Interrupts

A break interrupt stops the counter and inhibits input captures.

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See BFCR in the SIM section of this data sheet.

To allow software to clear status bits during a break interrupt, write a 1 to BCFE. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.

15.7 I/O Signals

The TIM module can share its pins with the general-purpose I/O pins. See [Figure 15-1](#) for the port pins that are shared.

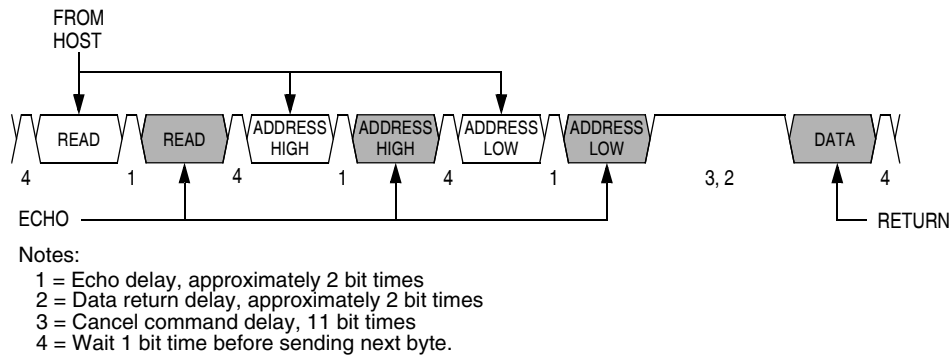


Figure 16-15. Read Transaction

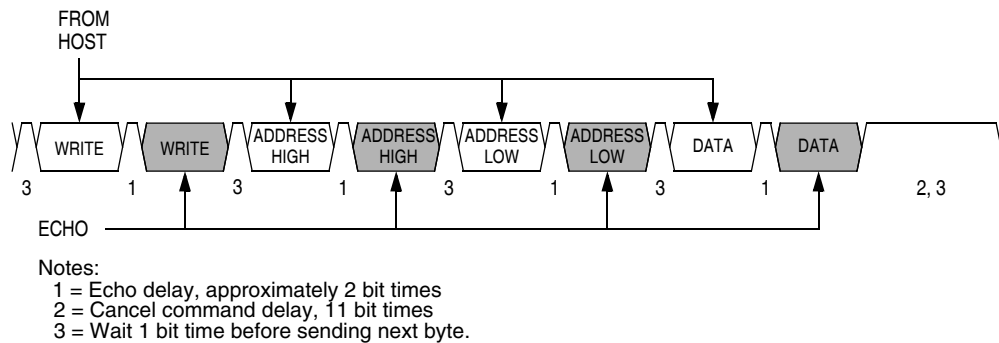


Figure 16-16. Write Transaction

A brief description of each monitor mode command is given in [Table 16-3](#) through [Table 16-8](#).

Table 16-3. READ (Read Memory) Command

Description	Read byte from memory
Operand	2-byte address in high-byte:low-byte order
Data Returned	Returns contents of specified address
Opcode	\$4A
<p style="text-align: center;">Command Sequence</p>	

17.13 ADC10 Characteristics

Characteristic	Conditions	Symbol	Min	Typ ⁽¹⁾	Max	Unit	Comment
Supply voltage	Absolute	V _{DD}	3.0	—	5.5	V	
Supply Current ADLPC = 1 ADLSMP = 1 ADCO = 1	V _{DD} ≤ 3.6 V (3.3 V Typ)	I _{DD} ⁽²⁾	—	55	—	μA	
	V _{DD} ≤ 5.5 V (5.0 V Typ)		—	75	—		
Supply current ADLPC = 1 ADLSMP = 0 ADCO = 1	V _{DD} ≤ 3.6 V (3.3 V Typ)	I _{DD} ⁽²⁾	—	120	—	μA	
	V _{DD} ≤ 5.5 V (5.0 V Typ)		—	175	—		
Supply current ADLPC = 0 ADLSMP = 1 ADCO = 1	V _{DD} ≤ 3.6 V (3.3 V Typ)	I _{DD} ⁽²⁾	—	140	—	μA	
	V _{DD} ≤ 5.5 V (5.0 V Typ)		—	180	—		
Supply current ADLPC = 0 ADLSMP = 0 ADCO = 1	V _{DD} ≤ 3.6 V (3.3 V Typ)	I _{DD} ⁽²⁾	—	340	—	μA	
	V _{DD} ≤ 5.5 V (5.0 V Typ)		—	440	615		
ADC internal clock	High speed (ADLPC = 0)	f _{ADCK}	0.40 ⁽³⁾	—	2.00	MHz	t _{ADCK} = 1/f _{ADCK}
	Low power (ADLPC = 1)		0.40 ⁽³⁾	—	1.00		
Conversion time ⁽⁴⁾ 10-bit Mode	Short sample (ADLSMP = 0)	t _{ADC}	19	19	21	t _{ADCK} cycles	
	Long sample (ADLSMP = 1)		39	39	41		
Conversion time ⁽⁴⁾ 8-bit Mode	Short sample (ADLSMP = 0)	t _{ADC}	16	16	18	t _{ADCK} cycles	
	Long sample (ADLSMP = 1)		36	36	38		
Sample time	Short sample (ADLSMP = 0)	t _{ADS}	4	4	4	t _{ADCK} cycles	
	Long sample (ADLSMP = 1)		24	24	24		
Input voltage		V _{ADIN}	V _{SS}	—	V _{DD}	V	
Input capacitance		C _{ADIN}	—	7	10	pF	Not tested
Input impedance		R _{ADIN}	—	5	15	kΩ	Not tested
Analog source impedance		R _{AS}	—	—	10	kΩ	External to MCU
Ideal resolution (1 LSB)	10-bit mode	RES	1.758	5	5.371	mV	V _{REFH} /2 ^N
	8-bit mode		7.031	20	21.48		
Total unadjusted error	10-bit mode	E _{TUE}	0	±1.5	±2.5	LSB	Includes quantization
	8-bit mode		0	±0.7	±1.0		
Differential non-linearity	10-bit mode	DNL	0	±0.5	—	LSB	
	8-bit mode		0	±0.3	—		
	Monotonicity and no-missing-codes guaranteed						

— Continued on next page